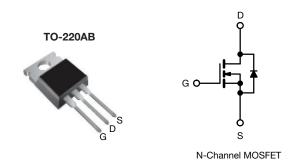
Vishay Siliconix

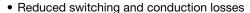
# **E Series Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	850			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.304		
Q <sub>g</sub> max. (nC)	53			
Q <sub>gs</sub> (nC)	8			
Q <sub>gd</sub> (nC)	16			
Configuration	Single			

## **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low effective capacitance (Co(er))



Avalanche energy rated (UIS)

 Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>



### **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP15N80AE-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			$V_{DS}$	800	V
Gate-source voltage			$V_{GS}$	± 30	v
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	- I <sub>D</sub>	13	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		8	Α
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	29	
Linear derating factor			1.25	W/°C	
Single pulse avalanche energy b		E <sub>AS</sub>	28	mJ	
Maximum power dissipation		P <sub>D</sub>	156	W	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	\//	
Reverse diode dv/dt <sup>d</sup>			14	V/ns	
Soldering recommendations (peak temperatur	re) c	For 10 s		260	°C

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 1.4 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	-	62	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.8	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static		-					
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.8	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2	-	4	V
Onto anima lankana		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 30 V		-	± 1	μΑ
Zana mata walta aa ahaa'a awaant		V <sub>DS</sub> =	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$		-	1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 640 V			-	10	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7.5 A	-	0.304	0.350	Ω
Forward transconductance a	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 7.5 A		-	5.9	-	S
Dynamic		-					
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1  MHz		-	1093	-	pF
Output capacitance	C <sub>oss</sub>			-	49	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	5	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	35	-	
Effective output capacitance, time related	C <sub>o(tr)</sub>			-	212	-	
Total gate charge	Qg			-	35	53	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 7.5 \text{ A}, V_{DS} = 640 \text{ V}$		8	-	nC
Gate-drain charge	Q <sub>gd</sub>	7			16	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 640 V, I <sub>D</sub> = 7.5 A,		-	15	30	ns
Rise time	t <sub>r</sub>			-	22	44	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		35	70	
Fall time	t <sub>f</sub>	1		-	30	60	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.2	0.5	1.1	Ω
<b>Drain-Source Body Diode Characteristic</b>							
Continuous source-drain diode current	I <sub>S</sub>	showing the	MOSFET symbol showing the		-	13	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	29	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 7.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 7.5 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	333	666	ns
Reverse recovery charge	Q <sub>rr</sub>			-	3.7	7.4	μC
Reverse recovery current	I <sub>RRM</sub>			-	19	_	A



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

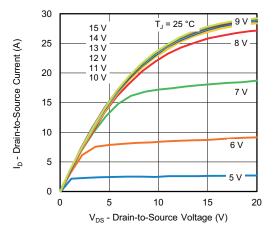


Fig. 1 - Typical Output Characteristics

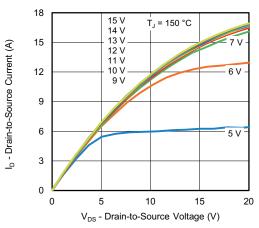


Fig. 2 - Typical Output Characteristics

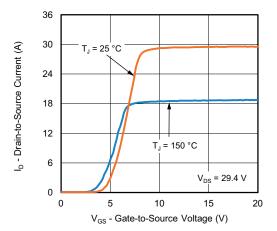


Fig. 3 - Typical Transfer Characteristics

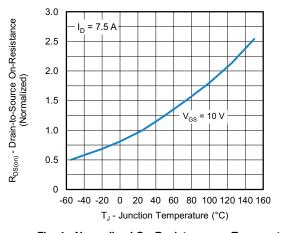


Fig. 4 - Normalized On-Resistance vs. Temperature

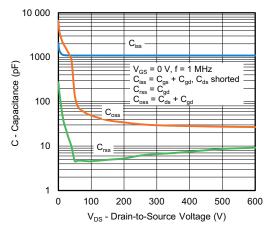


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

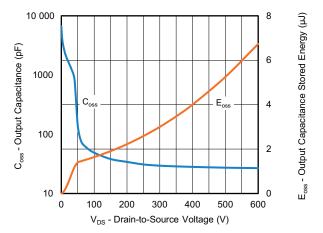


Fig. 6 - Coss and Eoss vs. VDS



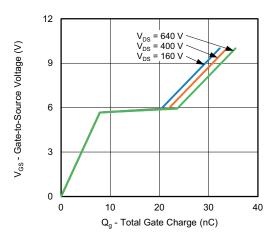


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

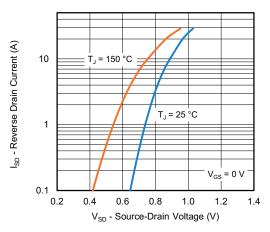


Fig. 8 - Typical Source-Drain Diode Forward Voltage

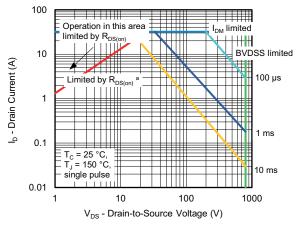


Fig. 9 - Maximum Safe Operating Area

## Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

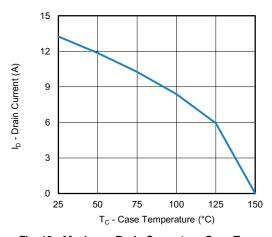


Fig. 10 - Maximum Drain Current vs. Case Temperature

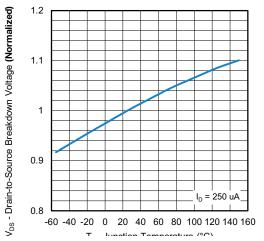


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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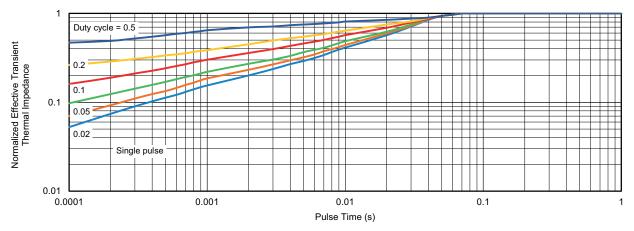


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

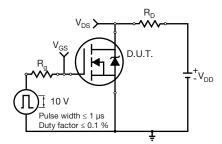


Fig. 13 - Switching Time Test Circuit

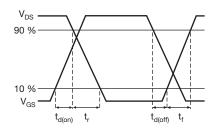


Fig. 14 - Switching Time Waveforms

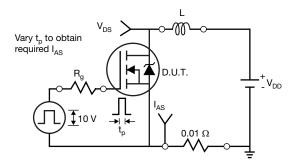


Fig. 15 - Unclamped Inductive Test Circuit

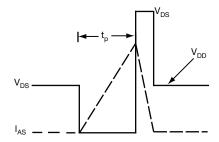


Fig. 16 - Unclamped Inductive Waveforms

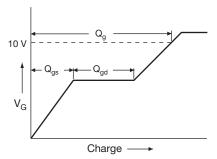


Fig. 17 - Basic Gate Charge Waveform

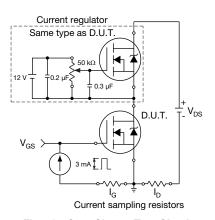
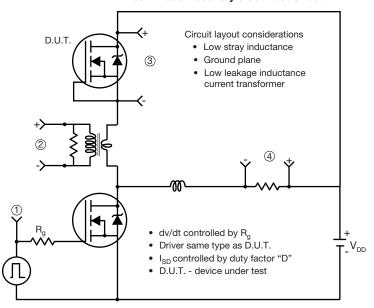


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dv/dt Test Circuit



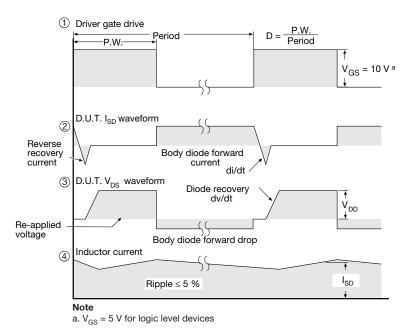


Fig. 19 - For N-Channel

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